

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5499774

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KEISUKE NAKATSUKA	04/12/2019
TOMOYA SANUKI	04/12/2019
TAKASHI MAEDA	04/19/2019
GO SHIKATA	04/23/2019
HIDEAKI AOCHI	04/10/2019
RECEIVING PARTY DATA	
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City:	MINATO-KU, TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16356980
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NAME OF SUBMITTER:	YASMEEN ELAGHA
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DATE SIGNED:	04/30/2019
Total Attachments: 8	
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ASSIGNMENT - WORLDWIDE

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto

TOSHIBA MEMORY CORPORATION
1-1, Shibaura 1-chome, Minato-ku,
Tokyo, Japan

its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries in and to the invention in

DATA LATCH CIRCUIT AND SEMICONDUCTOR MEMORY DEVICE

as set forth in this United States Patent Application

- executed concurrently herewith
- executed on _____
- Serial No. 16/356,980 filed March 18, 2019

said application for United States Letters Patent, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications and every priority right that is or may be predicated upon or arise from said inventions, said applications, and said Letters Patent; said Assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said Assignee or otherwise as said Assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America being hereby authorized to issue or transfer all said Letters Patent to said Assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right theretofore given, and that the undersigned will do all acts reasonably serving to ensure that the said inventions, patent applications and Letters Patent shall be held and enjoyed by said Assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said Assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said Assignee, to furnish said Assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

The undersigned hereby grant the firm of FOLEY & LARDNER LLP the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

<i>NAMES AND SIGNATURES OF INVENTORS</i>		
Name: Keisuke NAKATSUKA	Signature: <i>Keisuke Nakatsuka</i>	Date: 2019 - April .12
Name: Tomoya SANUKI	Signature: <i>Tomoya Sanuki</i>	Date: 2019. April .12
Name: Takashi MAEDA	Signature:	Date:
Name: Go SHIKATA	Signature:	Date:
Name: Hideaki AOCHI	Signature:	Date:
<i>NAMES AND SIGNATURES OF WITNESSES</i>		
Name:	Signature:	Date:
Name:	Signature:	Date:

Note: Prima facie evidence of execution may optionally be obtained by execution of this document before a U.S. Consul or before a local officer authorized to administer oaths whose authority is proved by a certificate from a U.S. Consul.

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Name: Keisuke NAKATSUKA	Signature:	Date:
Name: Tomoya SANUKI	Signature:	Date:
Name: Takashi MAEDA	Signature: <i>Takashi Maeda</i>	Date: <i>April 19, 2019</i>
Name: Go SHIKATA	Signature:	Date:
Name: Hideaki AOCHI	Signature:	Date:
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Name: Tomoya SANUKI	Signature:	Date:
Name: Takashi MAEDA	Signature:	Date:
Name: Go SHIKATA	Signature: <i>Go Shikata</i>	Date: <i>April 23, 2019</i>
Name: Hideaki AOCHI	Signature:	Date:
<i>NAMES AND SIGNATURES OF WITNESSES</i>		
Name:	Signature:	Date:
Name:	Signature:	Date:

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Name: Tomoya SANUKI	Signature:	Date:
Name: Takashi MAEDA	Signature:	Date:
Name: Go SHIKATA	Signature:	Date:
Name: Hideaki AOCHI	Signature: 	Date: Apr. 10, 2019
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